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Regarding to latest logic semiconductor manufacturing in Japan had been halted since 1995-2000 because of losing the business style change chance and kept only Japanese inside source for development work, They had lost its activity and market share. Many of Japanese semiconductor IDM company also had not chase Moore's scaling low because of lack of large investing and funding money with business scope. It was so obvious for the results, major semiconductor business had been gone and never back to Japan side. Even if they are strong but only Japanese semiconductor business industry are limited to both material and equipment supply for overseas customer, We say this as lost 30 years. Right now Japanese semiconductor business has only 15% of world market share of semiconductor as well as Europe industry. We now decided to challenge again to 2nm and beyond 2nm logic device manufacturing at inside of Japan, strongly assisted by Japanese and USA government. So that re-generating purpose, new semiconductor foundry Rapidus Corp. had established on 2022, targeting to product 2nm level semiconductor with advanced packaging technology on 2027. Rapidus has collaborated with IBM who is first 12'' wafer level inventor of 2nm logic in the world. Also collaborated with imec on 2022 for long term contract.. In this session I would like to explain current semiconductor situation in Japan and our company strategy for future and configuration shortly. Also mentioned to packaging technology with Chiplet.

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